CMOS IC


## Preliminary

## Overview

The LC82293 is an image memory controller that supports a wide range of applications such as video printers and video capture systems. It features a simple configuration and low cost.

## Features

- Can directly be connected to a YUV422 video bus, so that direct connection to various video decoders and video encoders is possible.
- Has a built-in horizontal sampling rate converter (SCR), so that reduction and enlargement by any factor is possible. (Example: $14.318 \mathrm{MHz} \rightarrow 13.5 \mathrm{MHz}$, etc.)
- 4Mbits DRAM/16Mbits DRAM directly connectable as image memories
- Built-in memory compression function for storing image data in compressed form in DRAM. NTSC and PAL images can be captured and displayed with an external 4Mbits DRAM. Of course, the memory compression function can be switched ON/OFF.
- Image captured to DRAM can be directly accessed from the CPU. In addition to PIO transfer, DMA transfer is also supported, and high-speed transfer is enabled by built-in FIFO.
- DMA supports both DRQ control mode and WAIT control mode. Connection to various DMA controllers is possible.
- Built-in IrDA 1.0 interface.
- Maximum operating clock of 18 MHz (Example: NTSC: 14.318 MHz, REC601:13.5 MHz)
- Internal supply voltage $=3.3 \mathrm{~V}$, pin supply voltage $=5 \mathrm{~V}$
- SQFP100 package


## Applications

Video printers, video capture sys̈tems, etc.

## Package Dimensions

unit: mm
31818-SQFP100



## DC Characteristics

## Absolute Maximum Ratings at $\mathbf{V}_{\text {SS }}=0 \mathrm{~V}$

| Parameter | Symbol | Conditions | Ratings | Unit |
| :---: | :---: | :---: | :---: | :---: |
| Maximum supply voltage ( 5 V system) | $V_{\text {DD5 }}$ max | $\mathrm{Ta}=25^{\circ} \mathrm{C}$ | -0.3 to +7.0 | V |
| Maximum supply voltage ( 3 V system) | $\mathrm{V}_{\mathrm{DD} 3}$ max | $\mathrm{Ta}=25^{\circ} \mathrm{C}$ | -0.3 to +4.6 | V |
| Inputoutput voltage | $V_{1}, V_{0}$ | $\mathrm{Ta}=25^{\circ} \mathrm{C}$ | -0.3 to $V_{\text {DD }}+0.3$ | V |
| Allowable power dissipation | Pd max | $\mathrm{Ta} \leq 70^{\circ} \mathrm{C}$ | 450 | mW |
| Operating temperature | Topr |  | -30 to +70 | ${ }^{\circ} \mathrm{C}$ |
| Storage temperature | Tstg |  | -55 to +125 | ${ }^{\circ} \mathrm{C}$ |
| Soldering temperature |  | 10 s | 235 | ${ }^{\circ} \mathrm{C}$ |
| Inputoutput current | 1,10 |  | $\pm 20$ | mA/cell |

Allowable Operating Ranges at $\mathbf{T a}=\mathbf{- 3 0}$ to $+\mathbf{7 0}^{\circ} \mathrm{C}, \mathrm{V}_{\text {SS }}=\mathbf{0} \mathrm{V}$

| Parameter | Symbol | Conditions | Aatings |  |  | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | min | typ | max |  |
| Supply voltage ( 5 V system) * | $V_{\text {DD5 }}$ |  | 4.5 | 5.0 | 5.5 | $V$ |
| Supply voltage (3.3 V system) | $V_{\text {DD3 }}$ |  | 3.0 | 3.3 | 3.6 | V |
| Input voltage range | $\mathrm{V}_{\text {IN }}$ |  | 0 |  | $V_{D D 5}\left(V_{\text {DD3 }}\right)$ | $\checkmark$ |

DC Characteristics at $\mathbf{T a}=-\mathbf{3 0}$ to $+70^{\circ} \mathrm{C}, \mathrm{V}_{\mathrm{SS}}=0 \mathrm{~V}, \mathrm{~V}_{\mathrm{DDS}}=4.5$ to 5.5 V

| Parameter | Symbol | Conditions | Ratings |  |  | Unit | Applicable pins |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | min | typ | max |  |  |
| High-level input voltage | $\mathrm{V}_{\mathrm{IH}}$ | TTL levels | 2.0 |  |  | $v$ | (1) |
| Low-level input voltage | $V_{\text {IL }}$ |  |  |  | 0.5 | V |  |
| High-level input voliage | $\mathrm{V}_{\mathrm{H}}$ | TTL levels Schmitt | 2.4 |  |  | V | (2) |
| Low-level input voltage | $\mathrm{V}_{\text {IL }}$ |  |  |  | 0.3 | V |  |
| High-level input voltage | $\mathrm{V}_{\mathrm{H}}$ | CMOS levels | $0.7 \mathrm{~V}_{\mathrm{DDS}}$ |  |  | V | (3) |
| Low-level input voltage | $V_{\text {IL }}$ |  |  |  | $0.2 V_{\text {DD5 }}$ | V |  |
| High-level output voltage | $\mathrm{V}_{\mathrm{OH}}$ | $\mathrm{IOH}^{\prime}=-2 \mathrm{~mA}$ | $V_{\text {DDS }}-0.8$ |  |  | V | (4) (7) (8) (9) |
| Low-level output voltage | $\mathrm{V}_{\mathrm{OL}}$ | $\mathrm{I}_{\mathrm{OL}}=2 \mathrm{~mA}$ |  |  | 0.4 | V |  |
| High-level output voltage | $\mathrm{V}_{\mathrm{OH}}$ | $\mathrm{I}_{\mathrm{OH}}=-4 \mathrm{~mA}$ | $V_{\text {DLS }}-0.8$ |  |  | V | (5) |
| Low-level output voltage | $\mathrm{V}_{\mathrm{OL}}$ | $\mathrm{l}_{\mathrm{OL}}=4 \mathrm{~mA}$ |  |  | 0.4 | V |  |
| High-level output voltage | V OH | $\mathrm{IOH}=-8 \mathrm{~mA}$ | $\mathrm{V}_{\mathrm{DD5} 5}-0.8$ |  |  | V | (6) |
| Low-level output voltage | $\mathrm{V}_{\mathrm{OL}}$ | $1 \mathrm{OL}=8 \mathrm{~mA}$ |  |  | 0.4 | $V$ |  |
| Input leak current | 11. | $V_{i}=V_{D D} V_{\text {S }}$ | -10 |  | +10 | $\mu \mathrm{A}$ | (1) (2) (3) (9) |
| Output leak current | $\mathrm{l} \mathrm{O}_{2}$ | During high-impedance output | -10 |  | +10 | $\mu \mathrm{A}$ | (7) (9) |
| Pull-up resistance | $\mathrm{R}_{\mathrm{UP}}$ |  | 70 | 140 | 280 | $\mathrm{k} \Omega$ | (8) |

The applicable pin sets are as follows.
( $1:$ TTL input) A3[3:0], FIELD, VSYNC, HSYNC, UARTIN, CLKGM, BCLK, IRIN
(2: TTL Schmitt input) ZCS, DACK, ZHRESET. ZRD, ZWR
(3: CMOS input) CLK
(4: Output 2 mA drive) MA[9:0], DRQ, IRQ. DIR, UARTOUT, IROUT
(5: Output 4 mA drive) ZWE
(6: Output 8 mA drive) ZRAS, ZCAS
(7: 3-state output 2 mA drive) ZWAIT
(8: Pull-up resistor built-in, bidirectional 2 mA drive) $\mathrm{Y}[7: 0], \mathrm{C}[7: 0], \mathrm{MD}[15: 0]$
(9: Bidirectional 2 mA drive) $\mathrm{D}[15: 0]$

